

MOSFET – Power, Dual N-Channel 60 V, 28 m Ω , 20 A

NVMFD5C680NL

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFD5C680NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	60	V
Gate-to-Source Voltage			V_{GS}	±20	V
Continuous Drain		T _C = 25°C	I _D	20	Α
Current R _{0JC} (Notes 1, 2, 3)	Steady	T _C = 100°C		15	
Power Dissipation	State	T _C = 25°C	P_{D}	24	W
R _{θJC} (Notes 1, 2)		T _C = 100°C		12	
Continuous Drain		T _A = 25°C	I _D	7.4	Α
Current R _{θJA} (Notes 1, 2, 3)	Steady State	T _A = 100°C		5.5	
Power Dissipation		T _A = 25°C	P_{D}	3.2	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.6	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \mu s$		I _{DM}	66	Α
Operating Junction and Storage Temperature		T _J , T _{stg}	-55 to + 175	°C	
Source Current (Body Diode)		I _S	20	Α	
Single Pulse Drain–to–Source Avalanche Energy ($T_J = 25^{\circ}C$, $I_{L(pk)} = 5 A$)			E _{AS}	47	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		TL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

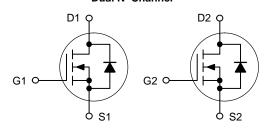
THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	6.27	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	46.6	

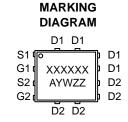
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
60 V	28 mΩ @ 10 V	20.4
60 V	41 mΩ @ 4.5 V	20 A

Dual N-Channel







A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condi	tion	Min	Тур	Max	Unit	
OFF CHARACTERISTICS					•		•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				29		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	T _J = 25 °C			10		
		V _{DS} = 60 V	T _J = 125°C			100	μΑ	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS}$	s = 20 V			100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D} = 13 \mu A$		1.2		2.2	V	
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-4.3		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 5 A		23	28		
		V _{GS} = 4.5 V	I _D = 5 A		33	41	mΩ	
Forward Transconductance	9FS	$V_{DS} = 15 \text{ V}, I_{D} = 5 \text{ A}$			50		S	
CHARGES, CAPACITANCES & GATE RESIS	TANCE				•	•	•	
Input Capacitance	C _{ISS}				350			
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1 MH:	z, V _{DS} = 25 V		150		pF	
Reverse Transfer Capacitance	C _{RSS}				6		1	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 48 V; I _D = 10 A			2.0			
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 10 A			5.0			
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 48 V; I _D = 10 A			0.8		nC	
Gate-to-Source Charge	Q _{GS}				1.2			
Gate-to-Drain Charge	Q_{GD}				0.8			
Plateau Voltage	V _{GP}				3.0		V	
SWITCHING CHARACTERISTICS (Note 5)					•		•	
Turn-On Delay Time	t _{d(ON)}				6.4			
Rise Time	t _r	VGS = 4.5 V. VD	s = 48 V.		25		1	
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 48 \text{ V},$ $I_{D} = 10 \text{ A}, R_{G} = 1.0 \Omega$			13		ns	
Fall Time	t _f				23			
DRAIN-SOURCE DIODE CHARACTERISTIC	s					•	•	
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.9	1.2	,,,	
		$I_S = 5 \text{ A}$	T _J = 125°C		0.8		V	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0$ V, $dIS/dt = 10$ A/ μ s, $I_{S} = 5$ A			17			
Charge Time	t _a				8		ns	
Discharge Time	t _b				9			
Reverse Recovery Charge	Q_{RR}				7		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width $\leq 300~\mu$ s, duty cycle $\leq 2\%$.

5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

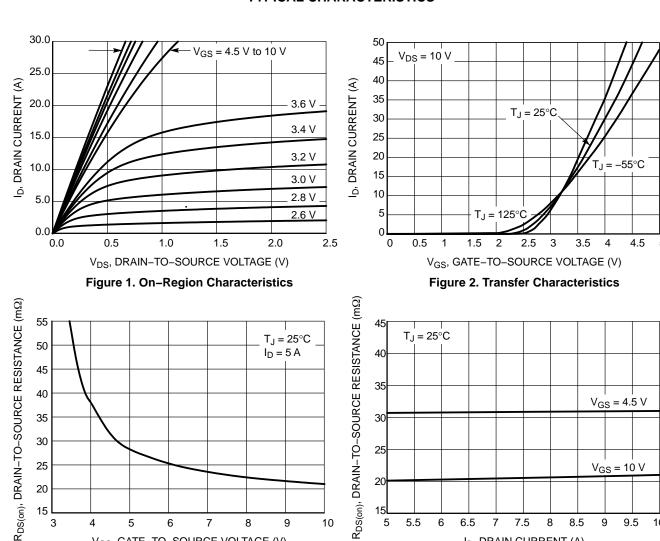


Figure 3. On-Resistance vs. Gate-to-Source

V_{GS}, GATE-TO-SOURCE VOLTAGE (V)

7

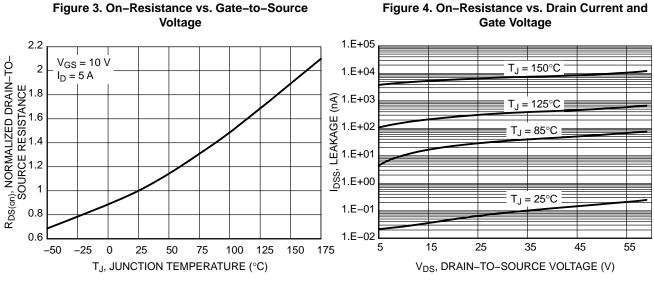
6

5

25

20 15

3



25

20

15

5

5.5

6

Figure 5. On-Resistance Variation with **Temperature**

Figure 6. Drain-to-Source Leakage Current vs. Voltage

7.5

ID, DRAIN CURRENT (A)

8

 $V_{GS} = 10 \text{ V}$

9.5

10

TYPICAL CHARACTERISTICS

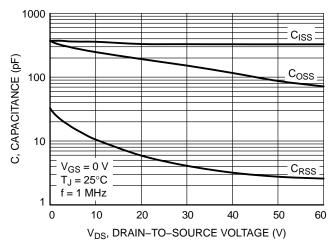


Figure 7. Capacitance Variation

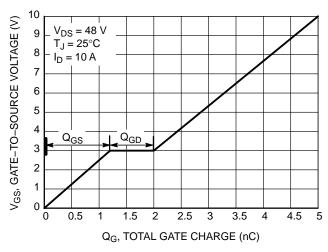


Figure 8. Gate-to-Source vs. Total Charge

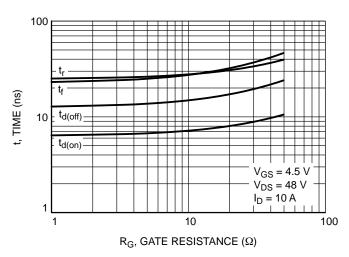


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

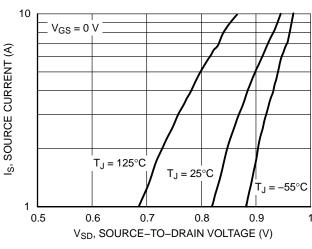


Figure 10. Diode Forward Voltage vs. Current

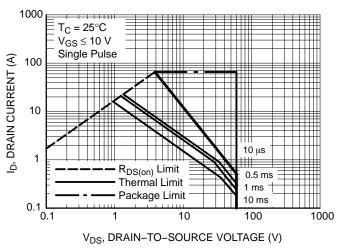


Figure 11. Maximum Rated Forward Biased Safe Operating Area

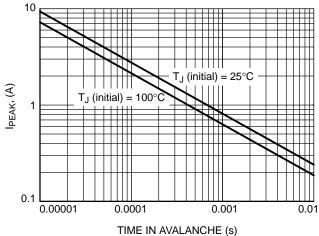


Figure 12. I_{PEAK} vs. Time in Avalanche

TYPICAL CHARACTERISTICS

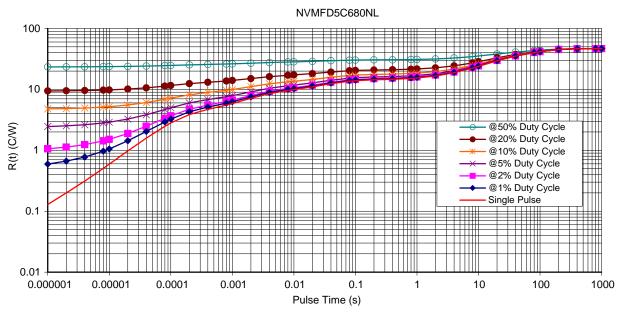


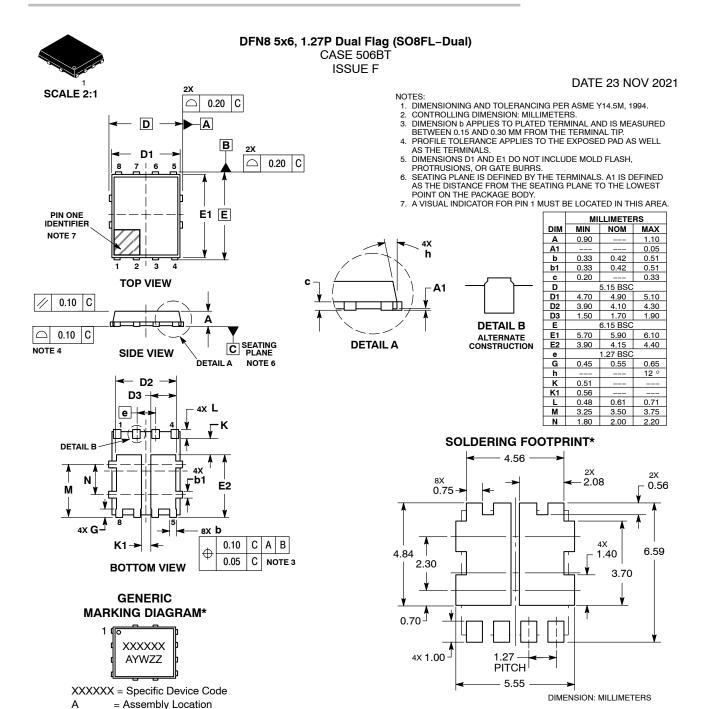
Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFD5C680NLT1G	5C680L	DFN8 (Pb-Free)	1500 / Tape & Reel
NVMFD5C680NLWFT1G	680LWF	DFN8 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





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DESCRIPTION:	DFN8 5X6, 1.27P DUAL FLAG (SO8FL-DUAL)		PAGE 1 OF 1		

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= Year

not follow the Generic Marking.

= Work Week

= Lot Traceability *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may

٧

W

ZZ

*For additional information on our Pb-Free strategy and soldering

Mounting Techniques Reference Manual, SOLDERRM/D.

details, please download the ON Semiconductor Soldering and

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